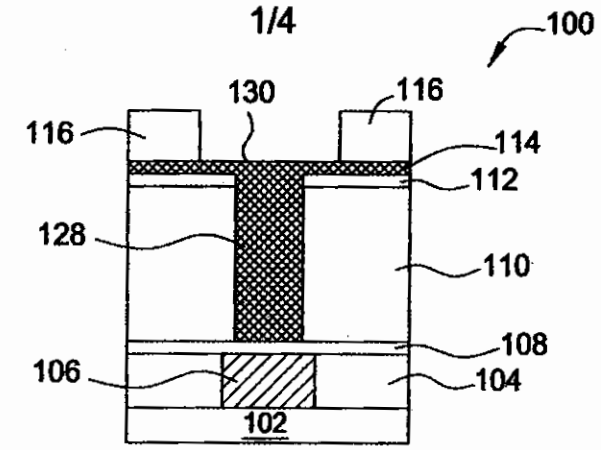


FIG. 1A
(PRIOR ART)

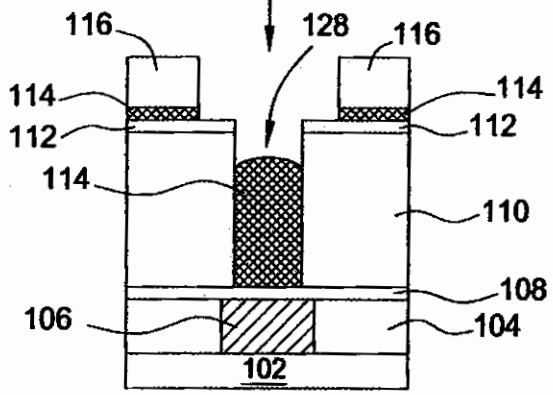


FIG. 1B
(PRIOR ART)

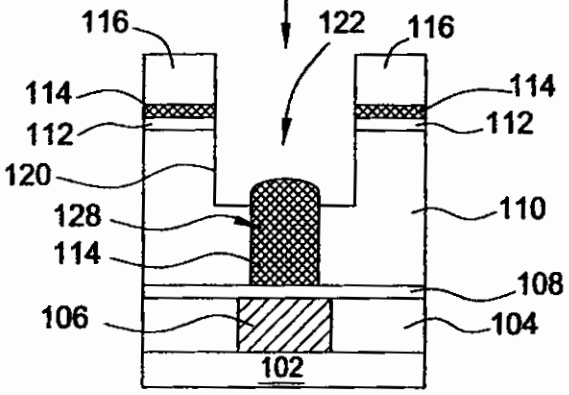


FIG. 1C
(PRIOR ART)

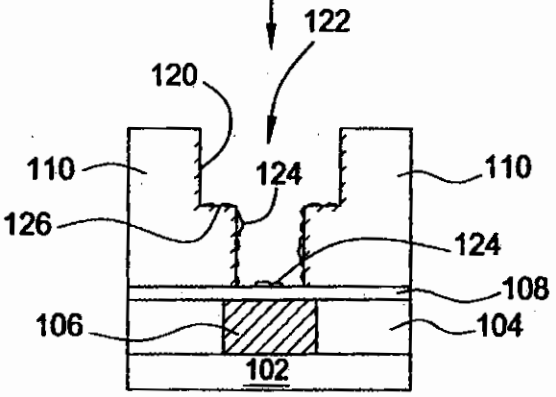


FIG. 1D
(PRIOR ART)

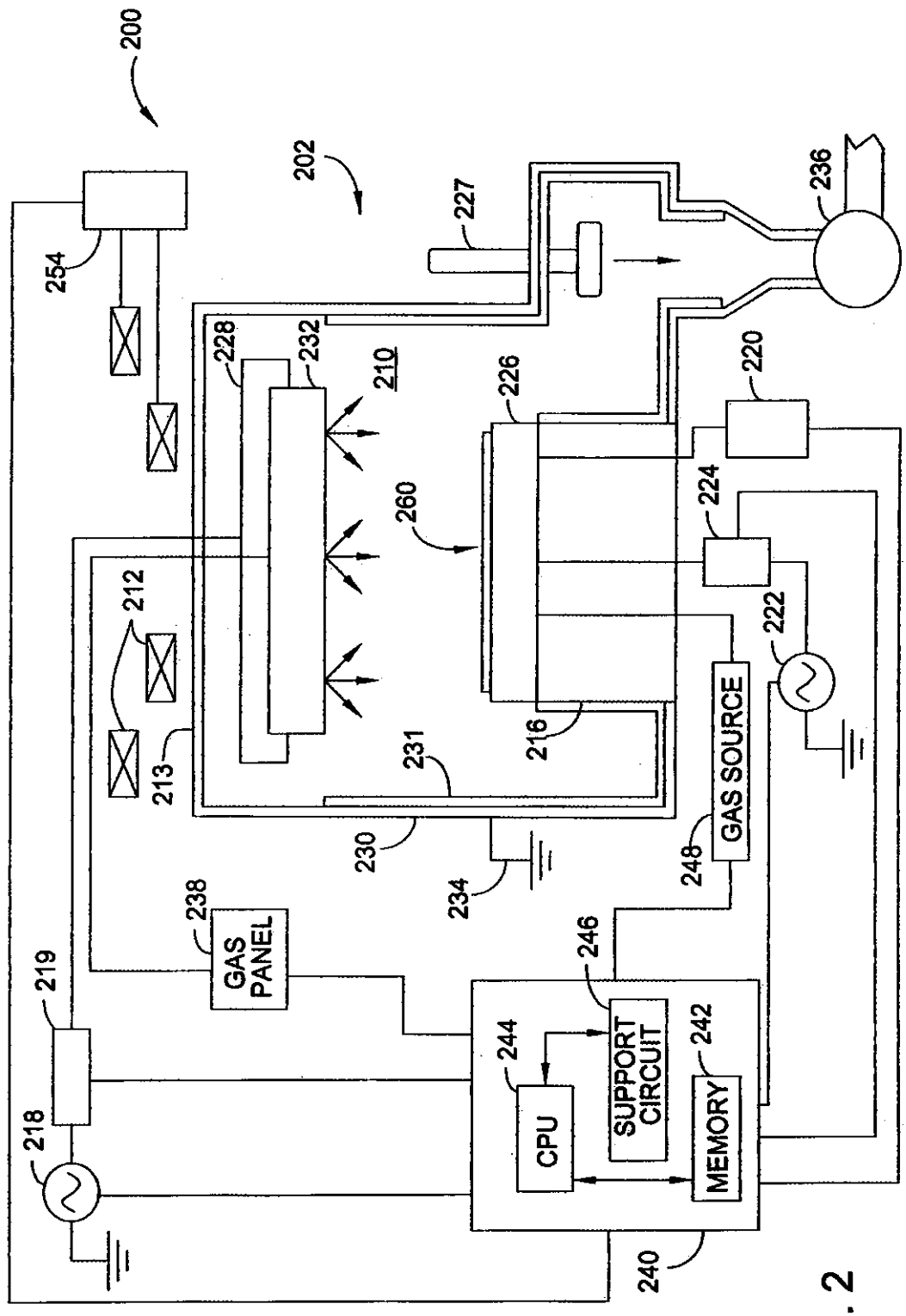

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GAS SOURCE
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GAS PANEL
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SUPPORT CIRCUIT
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CPU
MEMORY
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FIG. 2

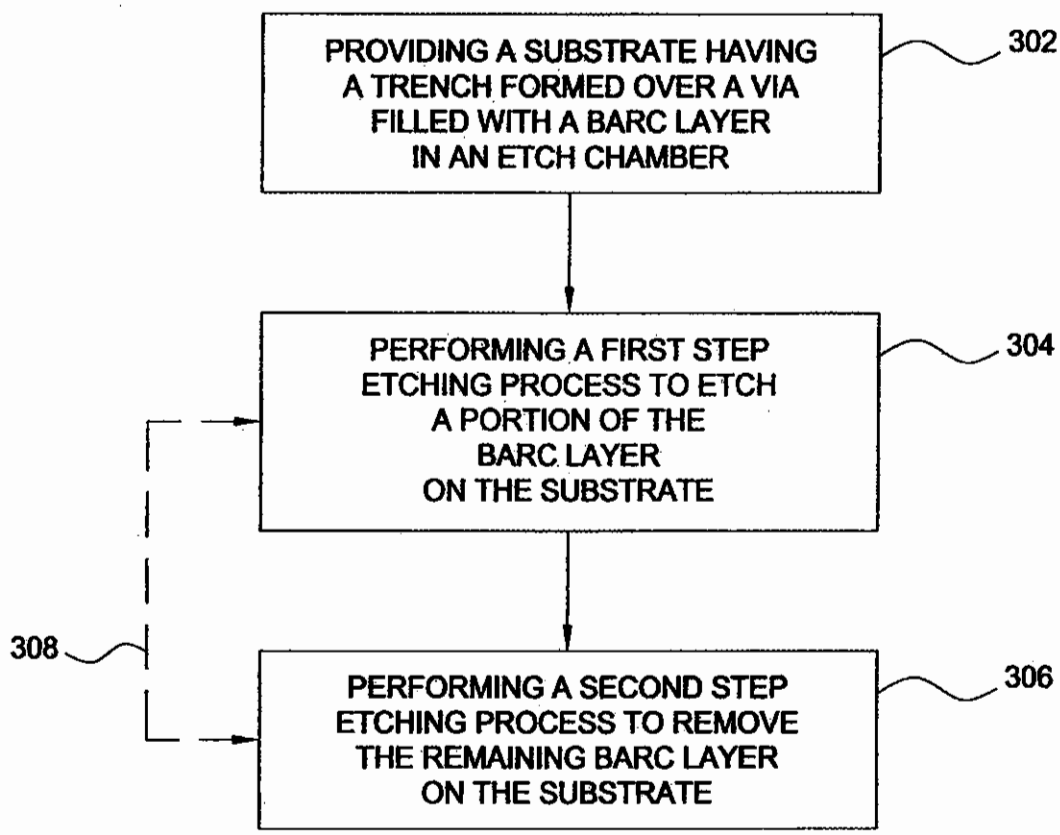

PROVIDING A SUBSTRATE HAVING A TRENCH FORMED OVER A VIA FILLED WITH A BARC LAYER IN AN ETCH CHAMBER
302
PERFORMING A FIRST STEP ETCHING PROCESS TO ETCH A PORTION OF THE BARC LAYER ON THE SUBSTRATE
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308
PERFORMING A SECOND STEP ETCHING PROCESS TO REMOVE THE REMAINING BARC LAYER ON THE SUBSTRATE
306

FIG. 3

FIG. 4A

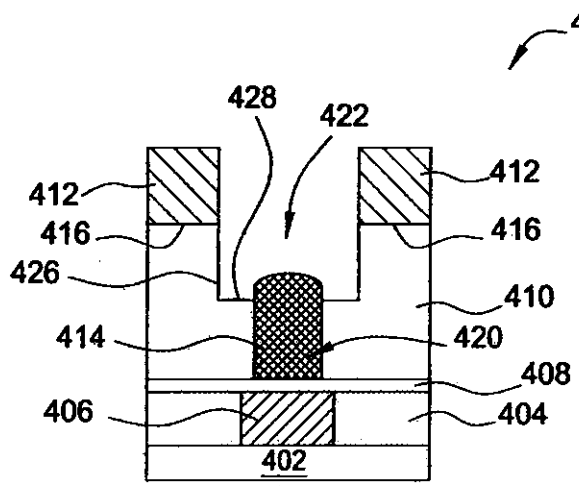
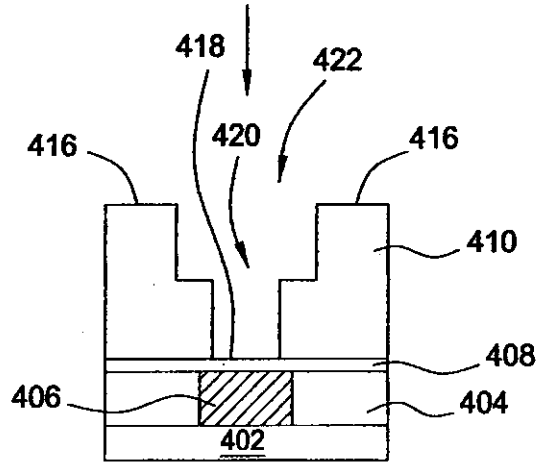

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FIG. 4B


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